

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die		Silicon Carbide (SiC)	409-21-2	0.59	100.0	1
			Subtotal	0.59	100	1
Wire	Impurity	Non hazardous		0	0.01	0
	Pure metal	Copper (Cu)	7440-50-8	0.21	99.99	0.36
			Subtotal	0.21	100	0.36
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.01	0.03	0.02
	Copper alloy	Zinc (Zn)	7440-66-6	0.06	0.15	0.1
	Copper alloy	Iron (Fe)	7439-89-6	0.88	2.29	1.49
	Copper alloy	Copper (Cu)	7440-50-8	37.29	96.97	63.19
	Copper alloy	Silver (Ag)	7440-22-4	0.22	0.56	0.36
			Subtotal	38.46	100	65.16
Mould Compound	Polymer	Epoxy Phenol Novolac resin (generic)	28064-14-4	2.06	3.5	3.49
	Filler	Silica -amorphous-	7631-86-9	4.71	8.0	7.98
	Filler	Silica fused	60676-86-0	47.07	80.0	79.76
	Carbon Black	Carbon black	1333-86-4	0.29	0.5	0.5
	Polymer	Epoxy resin system		4.71	8.0	7.98
			Subtotal	58.84	100	99.71
Post-plating	Pure metal	Tin (Sn)	7440-31-5	1.83	100.0	3.1
			Subtotal	1.83	100	3.1
Die Attach	Hardener	Hardener		0	5.0	0.01
	Phenolic resin	Phenolic resin		0	5.0	0.01
	Epoxy resin	Epoxy resin system		0	5.0	0.01
	Lead alloy	Silver (Ag)	7440-22-4	0.07	85.0	0.12
			Subtotal	0.07	100	0.15
			Total	100	100	169.48

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